



# LTCC

Low temperature co-fired ceramic Package

## DESCRIPTION

Lingsen LTCC package is a ceramic substrate based plastic package. It is available in pin count from 4 to higher pin counts based on the size of designed substrate. It is ideal to be used in the packaging of RF, wireless, blue tooth, portable as well as high-end networking and computing applications products.

## APPLICATIONS

- RF/ Wireless/ Blue tooth/ GPS
- Networking and computing applications products.

## SPECIFICATIONS

Epoxy./ Pb free solder  
 Gold Wire: 99.99%Au.  
 Marking: Laser Mark  
 Packing: Tray

## FEATURES

- Low profile
- Package body size is flexible by substrate design
- JEDEC standard compliant

## CROSS-SECTION

